

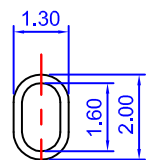
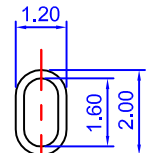
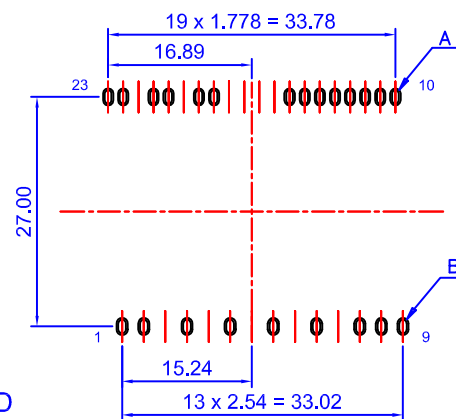
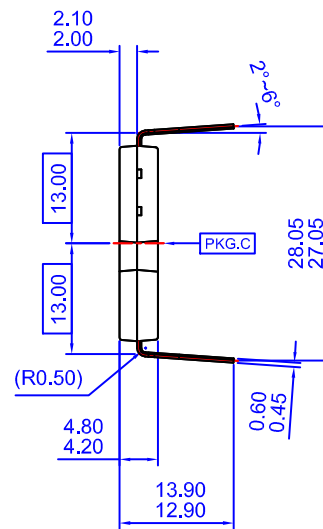
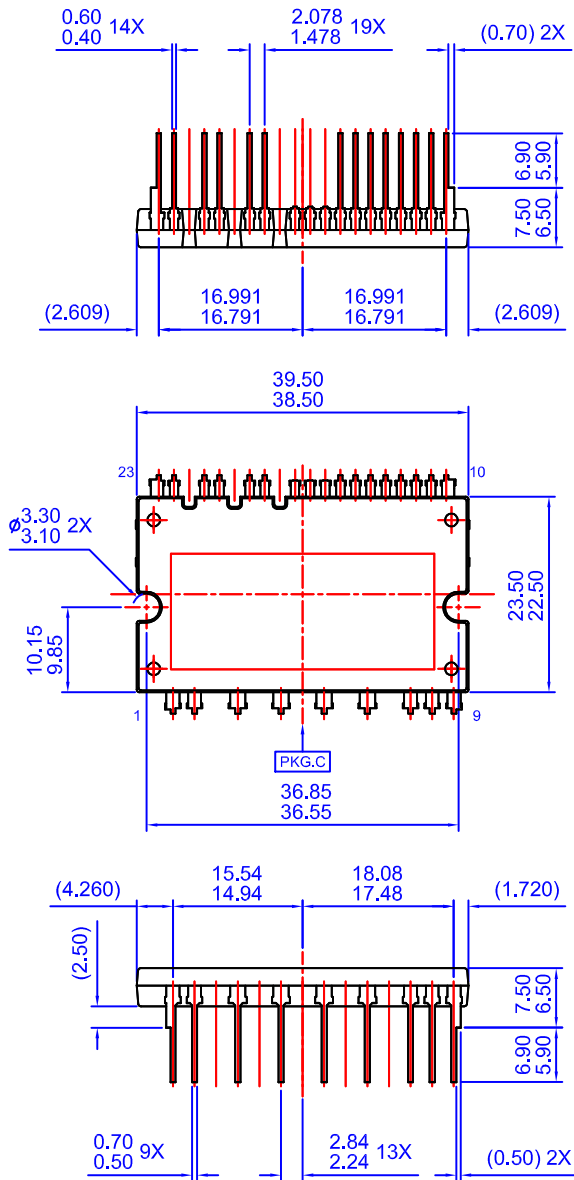
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®



SPMAA-F26 / 23LD, SPM26-AAF (23LEAD), LONG LEAD, DUAL FORM STAND OFF OPTION 2.5MM CASE MODEV ISSUE O

DATE 31 JAN 2017



- NOTES: UNLESS OTHERWISE SPECIFIED
- A) THIS PACKAGE DOES NOT COMPLY TO ANY CURRENT PACKAGING STANDARD
 - B) ALL DIMENSIONS ARE IN MILLIMETERS
 - C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS
 - D) () IS REFERENCE

LAND PATTERN RECOMMENDATIONS

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	SPMAA-F26 / 23LD, LONG LEAD, DUAL STANDOFF OPTION 2.5MM	PAGE 1 OF 2

